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Nagasaka et al.

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(54) **WAFER ATTRACTING PLATE**

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(**) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (9) Cl.** **13-03**

(52) **U.S. Cl.** **D13/180**

(58) **Field of Classification Search** D13/180;
D26/2; 257/79, 80, 81, 88, 89, 95, 98, 99,
257/100; 313/483, 498, 500; 362/555, 800
See application file for complete search history.

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(57) **CLAIM**

The ornamental design for wafer attracting plate, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of the wafer attracting plate, showing our design;

FIG. 2 is a front view thereof;

FIG. 3 is a rear view thereof;

FIG. 4 is a plan view thereof;

FIG. 5 is a bottom view thereof;

FIG. 6 is a left side view thereof;

FIG. 7 is a right side view thereof; and,

FIG. 8 is a section view taken along a line as shown in FIG. 2.

1 Claim, 6 Drawing Sheets

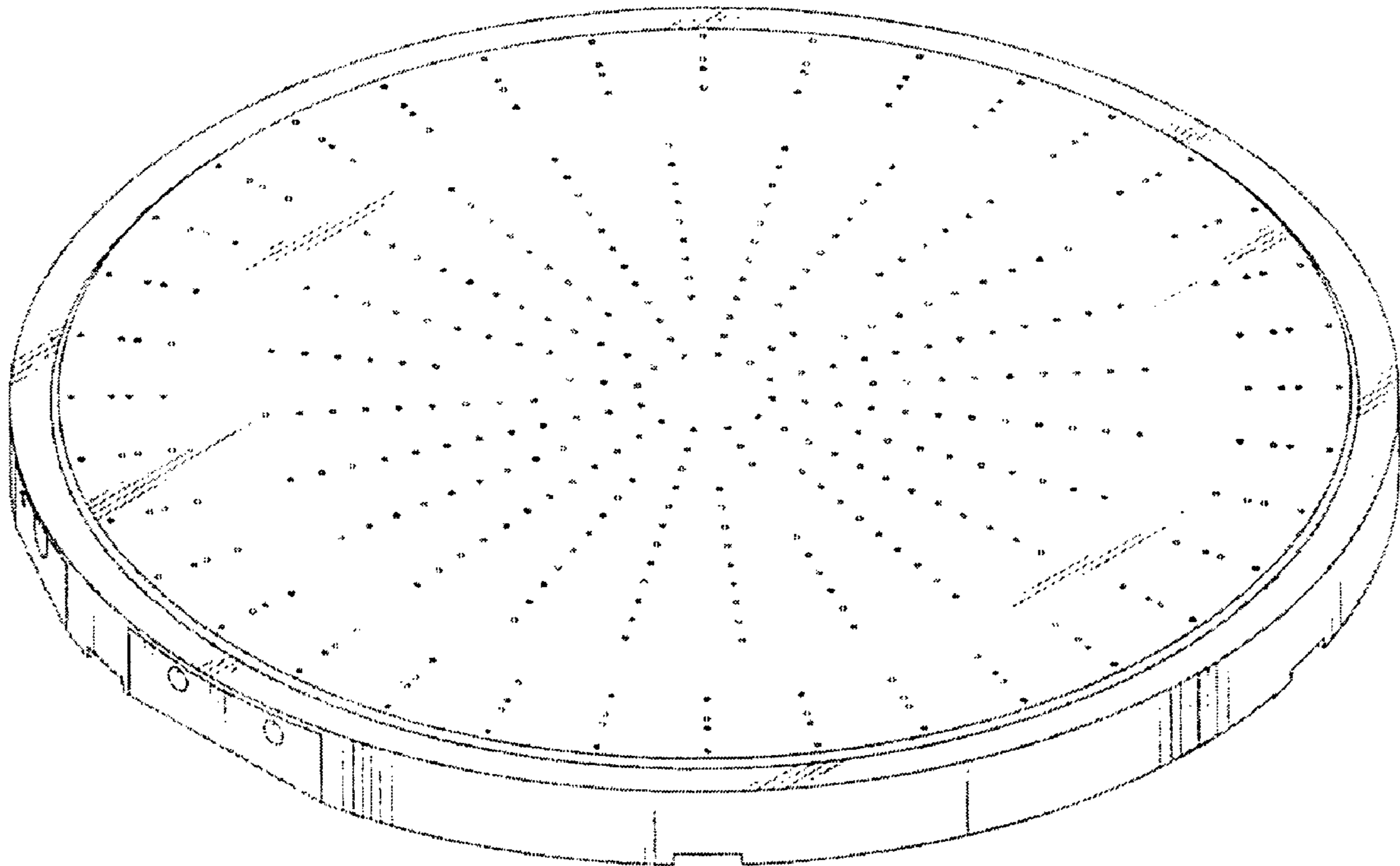


FIG. 1

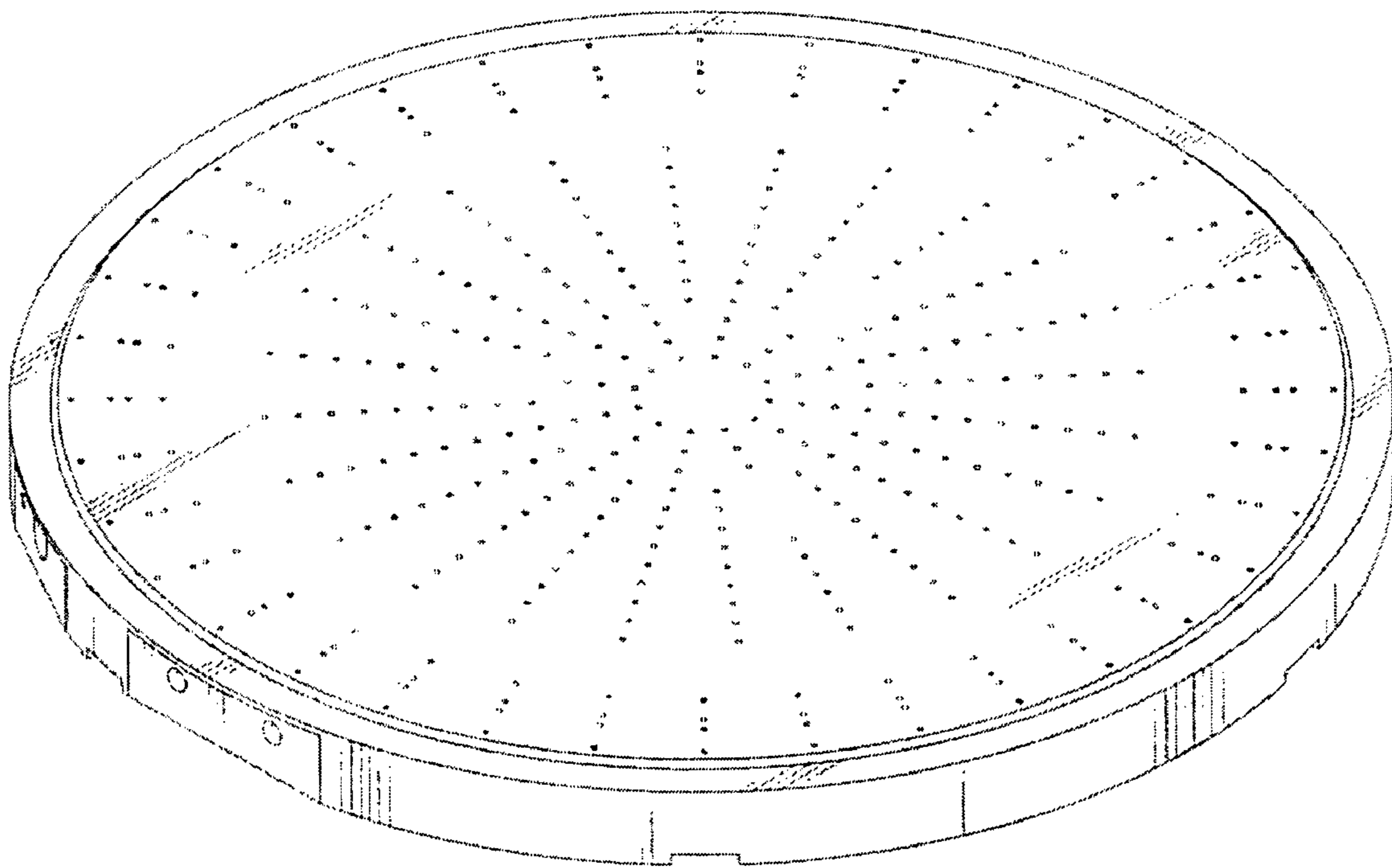


FIG.2

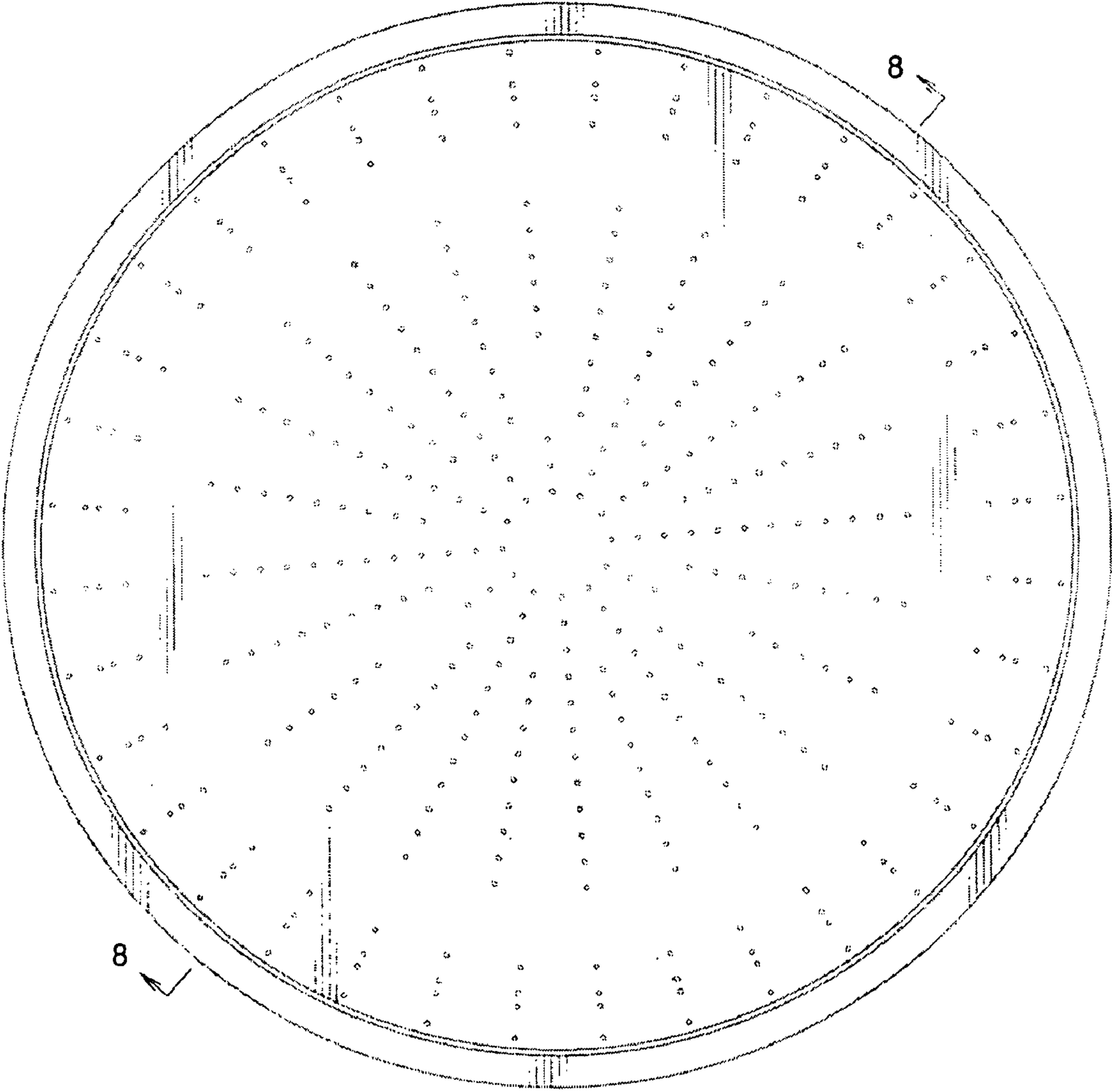


FIG.3

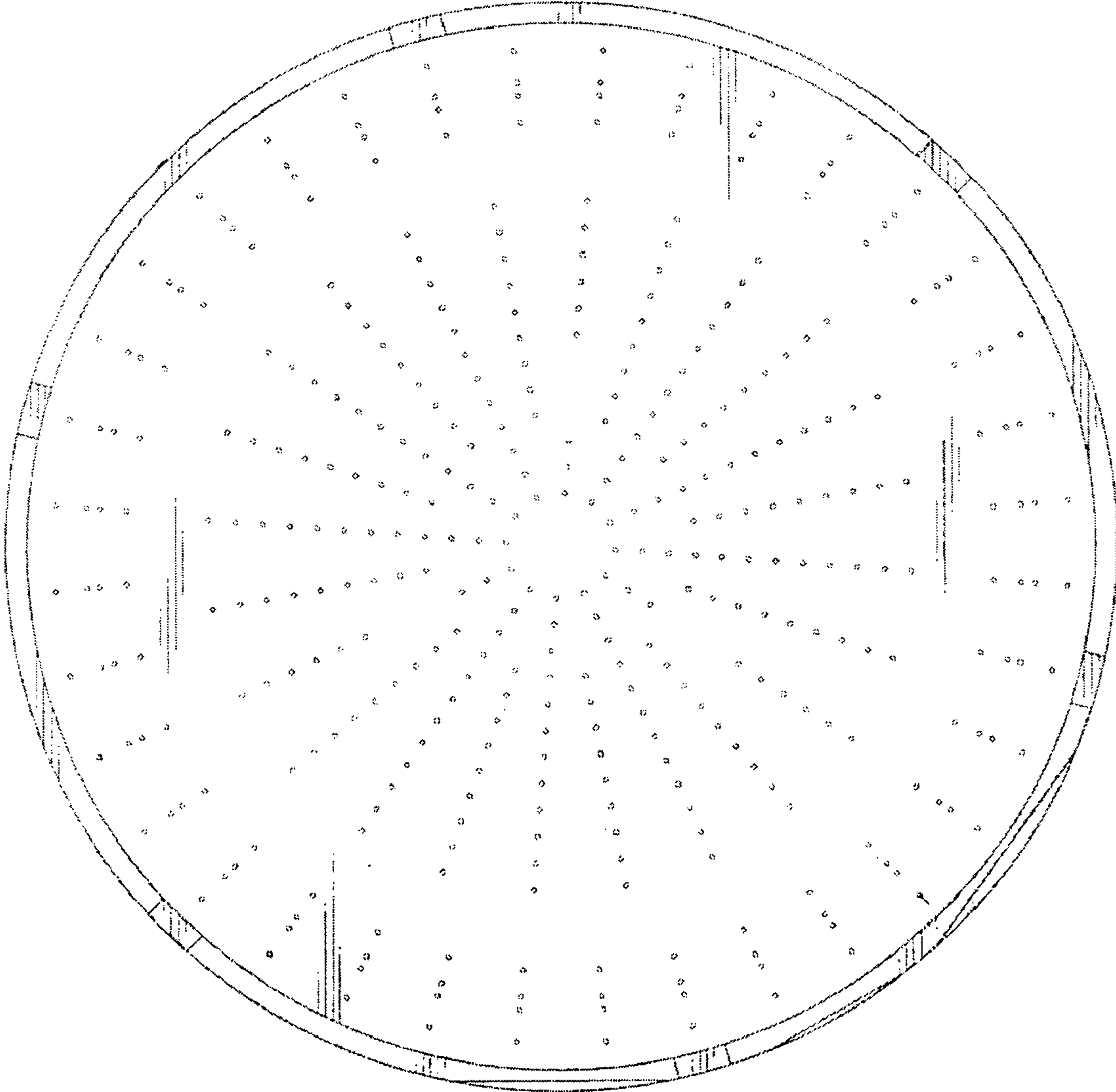


FIG.4

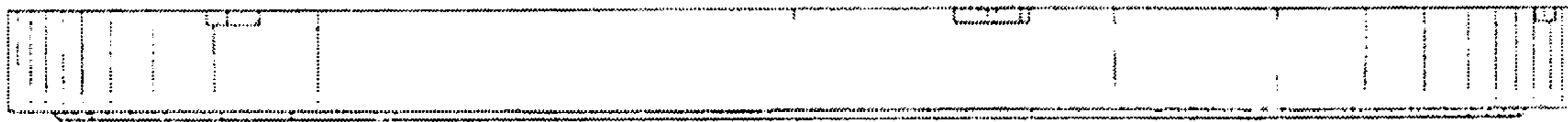


FIG.5

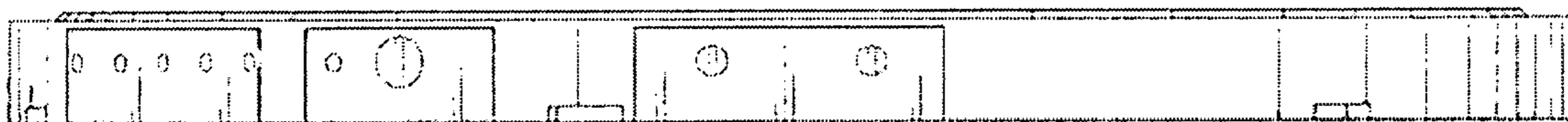


FIG. 6



FIG. 7



FIG.8

